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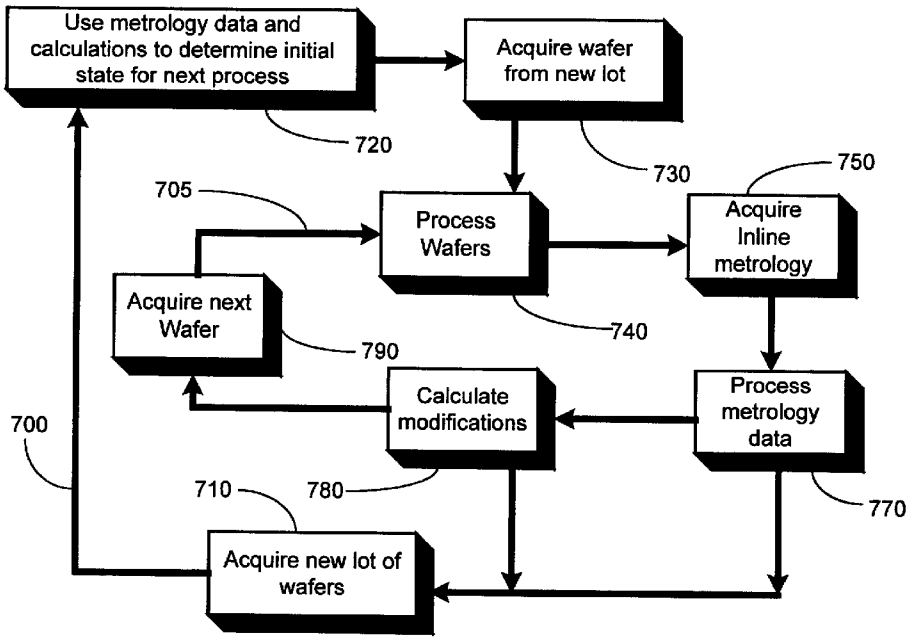
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(54) Title: METHOD AND APPARATUS FOR CASCADE CONTROL USING INTEGRATED METROLOGY



(57) Abstract: A method and an apparatus for performing cascade control of processing of semiconductor wafers (105). A first semiconductor wafer (105) for processing is received, A second semiconductor wafer (105) for processing is received. A cascade processing operation upon the first and the second semiconductor wafers (105) is performed, wherein the cascade processing operation comprises acquiring pre-process metrology data related to the second semiconductor wafer (105) during at least a portion of a time period wherein the first semiconductor wafer (105) is being processed.

WO 03/038888 A2